

Cypress Semiconductor Product Qualification Report

QTP # 151304 VERSION
May, 2015**

CCG1 Device Family	
S8PF-10R Technology, Fab 4 CMI	
CYPD1103**	USB Type-C Port Controller with Power Delivery
CYPD1104**	
CYPD1105**	
CYPD1120**	
CYPD1121**	
CYPD1122**	
CYPD1131**	
CYPD1132**	
CYPD1134**	

FOR ANY QUESTIONS ON THIS REPORT, PLEASE CONTACT
reliability@cypress.com or via a CYLINK CRM CASE

Prepared By:
Josephine Pineda (JYF)
Reliability Engineer

Reviewed By:
Rene Rodgers (RT)
Reliability Manager

Approved By:
Don Darling (DCDA)
Reliability Director



PRODUCT QUALIFICATION HISTORY

QTP Number	Description of Qualification Purpose	Date
083401	Qualify SONOS S8DI-5R Technology in Fab 4 using PSoC 8C20066BC Krypton Device	Jan 2009
113905	Qualify device 8C20400BC S8P12-10P Technology Fabricated at Fab4 (CMI)	Jan 2012
151304	Qualify CCG1 device (8C44100A/ 8C44110A/ 8F44100A), S8PF-10R Technology in Fab 4	Apr 2015

PRODUCT DESCRIPTION (for qualification)	
Qualification Purpose: To qualify CCG1 device (8C44100A/ 8C44110A/ 8F44100A), S8PF-10R technology in Fab 4	
Marketing Part #:	CYPD1103**/ CYPD1104**/ CYPD1105**/ CYPD1120**/ CYPD1121**/ CYPD1122**CYPD1131**/ CYPD1132** CYPD1134**
Device Description:	USB Type-C Port Controller with Power Delivery
Cypress Division:	Cypress Semiconductor – Data Communication Division

TECHNOLOGY/FAB PROCESS DESCRIPTION			
Number of Metal Layers:	5	Metal Composition:	Metal 1: 100A Ti / 3200A Al 0.5%Cu / 300A TiW Metal 2: 100A Ti/3,200A Al 0.5% Cu/350A TiW Metal 3: 150A Ti / 7200A Al 0.5%Cu / 350A TiW Metal 4: 150A Ti / 7200A Al 0.5%Cu / 350A TiW Metal 5: 300A Ti / 12000A Al 0.5%Cu / 300A TiW
Passivation Type and Thickness:	1,000A NFUSOX /6,000A Nitride		
Generic Process Technology/Design Rule (μ -drawn):	S8 / 0.13u		
Gate Oxide Material/Thickness (MOS):	SiO ₂ / 32A & SiO ₂ / 120A		
Name/Location of Die Fab (prime) Facility:	Fab 4, CMI-Minnesota		
Die Fab Line ID/Wafer Process ID:	S8PF-10R		

PACKAGE AVAILABILITY

PACKAGE	ASSEMBLY FACILITY SITE	WIRE MATERIAL	QTP NUMBER
16L SOIC (150 mils)	CML-RA	Au	QTP# 150801
40L QFN	CML-RA	CuPd	QTP# 151904
35 WLCSP	DT-Philippines	-	QTP# 144402



MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION

Package Designation:	SZ161
Package Outline, Type, or Name:	16L SOIC (150 mils)
Mold Compound Name/Manufacturer:	KE-G3000DA/Kyocera
Mold Compound Flammability Rating:	UL-94 V-0
Oxygen Rating Index: >28%	54%
Leadframe Designation	FMP
Lead Frame Material:	Copper
Lead Finish, Composition / Thickness:	NiPdAu
Die Backside Preparation Method/Metallization:	Backgrind
Die Separation Method:	Saw
Die Attach Supplier:	Henkel
Die Attach Material:	QMI 519
Bond Diagram Designation:	001-95720
Wire Bond Method:	Thermosonic
Wire Material/Size:	Au/ 0.8 mil
Thermal Resistance Theta JA °C/W:	85°C/W
Package Cross Section Yes/No:	No
Assembly Process Flow:	11-21099
Name/Location of Assembly (prime) facility:	CML-RA
MSL Level	3
Reflow Profile	260C

ELECTRICAL TEST / FINISH DESCRIPTION

Test Location:	CML-RA
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MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION

Package Designation:	LQ40A
Package Outline, Type, or Name:	40L Quad Flat No Lead (6x6x0.6mm)
Mold Compound Name/Manufacturer:	7470LA/Nitto
Mold Compound Flammability Rating:	UL-94 V-0
Oxygen Rating Index: >28%	54%
Leadframe Designation	FMP
Lead Frame Material:	Copper
Lead Finish, Composition / Thickness:	NiPdAu
Die Backside Preparation Method/Metallization:	Backgrind
Die Separation Method:	Saw
Die Attach Supplier:	Henkel
Die Attach Material:	QMI 519
Bond Diagram Designation:	001-72734
Wire Bond Method:	Thermosonic
Wire Material/Size:	CuPd/ 0.8 mil
Thermal Resistance Theta JA °C/W:	15.34°C/W
Package Cross Section Yes/No:	Yes
Assembly Process Flow:	11-21099
Name/Location of Assembly (prime) facility:	CML-RA
MSL Level	3
Reflow Profile	260C

ELECTRICAL TEST / FINISH DESCRIPTION

Test Location:	CML-RA
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MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION	
Package Designation:	FN35A
Package Outline, Type, or Name:	35-Ball Wafer Level Chip Scale Package (WLCSP) (3.23 x 2.10 x 0.55mm)
Die Backside Preparation Method:	Backgrind
Die Separation Method:	Saw
Solder Ball/Bump Material:	SAC405
Bonding Method:	Bump/ RDL
Bond Diagram Designation:	001-95722
Thermal Resistance Theta JA °C/W:	28°C/W
Package Cross Section Yes/No:	N/A
Assembly Process Flow:	001-69882
Name/Location of Assembly (prime) facility:	DT-Philippines
MSL Level	1
Reflow Profile	260C

ELECTRICAL TEST / FINISH DESCRIPTION	
Test Location:	DT-Philippines

Note: Please contact a Cypress Representative for other package availability.

RELIABILITY TESTS PERFORMED PER SPECIFICATION REQUIREMENTS

Stress/Test	Test Condition (Temp/Bias)	Result P/F
Acoustic Microscopy	J-STD-020 Precondition: JESD22 Moisture Sensitivity Level (192 Hrs., 30 °C, 60% RH, 260°C Reflow)	P
Age Bond Strength	200C, 4hrs MIL-STD-883, Method 883-2011	P
Bond Pull	MIL-STD-883 – Method 2011,	P
Data Retention	150°C, No Bias JESD22-A117 and JESD22-A103	P
Dye Penetrant Test	Test to determine the existence and extent of cracks, Criteria: No Package Crack	P
Dynamic Latch-up	125°C, 8.5V JESD78	P
Electrostatic Discharge Charge Device Model (ESD-CDM)	500V/1,000V/1,250V JESD22-C101	P
Electrostatic Discharge Human Body Model (ESD-HBM)	1,100V/1,600V/2,200V /3,300V JESD22, Method A114	P
Electrostatic Discharge Machine Model (ESD-MM)	200V, 220V, 275V, 330V JESD22-A115	P
Endurance Test	MIL-STD-883, Method 883-1033/ JESD22-A117	P
High Accelerated Saturation Test (HAST)	JEDEC STD 22-A110: 130°C, 85% RH, 5.25V/5.5V Precondition: JESD22 Moisture Sensitivity Level (192 Hrs., 30 °C, 60% RH, 260°C Reflow)	P
High Temperature Operating Life Early Failure Rate	Dynamic Operating Condition, Vcc Max=2.1V/2.07V, 150°C JESD22-A-108	P
High Temperature Operating Life Early Failure Rate, Regulator On	Dynamic Operating Condition, Vcc Max=5V, 125°C/150°C Dynamic Operating Condition, Vcc Max=2.07V/6V, 150°C JESD22-A-108	P
High Temperature Operating Life Latent Failure Rate	Dynamic Operating Condition, Vcc Max=2.1V/2.07V, 150°C JESD22-A-108	P
High Temperature Steady State life	Static Operating Condition, Vcc Max=2.1V, 150°C JESD22-A-108	P
Internal Visual	MIL-STD-883-2014	P
Low Temperature Operating Life	Dynamic Operating Condition, -30°C, 2.1V JESD22-A108	P
Low Temperature Storage Life	-40°C, No Bias	P
Pressure Cooker	JESD22-A102:121°C /100%RH, 15 PSIG Precondition: JESD22 Moisture Sensitivity Level (192 Hrs., 30 °C, 60% RH, 260°C Reflow)	P
SEM Analysis	MIL-STD-883, Method 2018	P
Static Latch-up	85C/125C, +/-140mA 85C, +/-180mA 85C, +/- 200mA JESD 78	P
Temperature Cycle	MIL-STD-883, Method 1010, Condition C, -65°C to 150°C Precondition: JESD22 Moisture Sensitivity Level (192 Hrs., 30 °C, 60% RH, 260°C Reflow)	P
Thermal Shock	MIL-STD-883, Method 1011, Condition B, -55°C to 125°C and JESD22-A106, Condition C, -55°C to 125°C	P

RELIABILITY FAILURE RATE SUMMARY

Stress/Test	Device Tested/ Device Hours	# Fails	Activation Energy	Thermal AF ³	Failure Rate
High Temperature Operating Life Early Failure Rate	4,491 Devices	0	N/A	N/A	0 PPM ⁽¹⁾
High Temperature Operating Life Long Term Failure Rate	718,500 DHRs	0	0.7	170	8 FIT ⁽²⁾

¹ Assuming an ambient temperature of 55°C and a junction temperature rise of 15°C.

² Chi-squared 60% estimations used to calculate the failure rate.

³ Thermal Acceleration Factor is calculated from the Arrhenius equation

$$AF = \exp \left[\frac{E_A}{k} \left[\frac{1}{T_2} - \frac{1}{T_1} \right] \right]$$

where:

E_A = The Activation Energy of the defect mechanism.

K = Boltzmann's constant = 8.62x10⁻⁵ eV/Kelvin.

T₁ is the junction temperature of the device under stress and T₂ is the junction temperature of the device at use conditions.

(1) Early Failure Rate was computed from QTP# 151304

(2) Long Term Failure Rate was computed from QTP# 083401, QTP#113905 and QTP# 151304



Reliability Test Data
QTP #: 083401

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: ACOUSTIC, MSL3							
CY8C20466 (8C20466AC)	4810486	610828990	Malaysia-CA	COMP	15	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	COMP	15	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	COMP	15	0	
STRESS: AGE BOND STRENGTH							
CY8C20566 (8C20566AC)	4827949	610844164	CML-R	COMP	3	0	
CY8C20466 (8C20466AC)	4804681	610822808	Malaysia-CA	COMP	3	0	
CY8C20666 (8C20666AC)	4836589	610852813	Malaysia-CA	COMP	3	0	
STRESS: DATA RETENTION, PLASTIC, 150C							
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	500	77	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	1000	77	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	500	78	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	1000	78	0	
CY8C20566 (8C20566AC)	4836589	610851914	CML-R	500	78	0	
CY8C20566 (8C20566AC)	4836589	610851914	CML-R	1000	78	0	
STRESS: ENDURANCE							
CY8C20566 (8C20566AC)	4810486	610830786	CML-R	168	77	0	
CY8C20566 (8C20566AC)	4815537	610835437	CML-R	168	77	0	
CY8C20566 (8C20566AC)	4827949	610844164	CML-R	168	79	0	
CY8C20566 (8C20566AC)	4835945	610848270	CML-R	168	78	0	
CY8C20566 (8C20566AC)	4836589	610851914	CML-R	168	76	0	
STRESS: ESD-CHARGE DEVICE MODEL, (500V)							
CY8C20566 (8C20566AC)	4810486	610830371	CML-R	500	9	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	500	9	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	500	9	0	
STRESS: SEM CROSS SECTION							
CY8C20066 (8C20066AC)	4810486	N/A	N/A	COMP	1	0	
STRESS: STATIC LATCH-UP (85C, 8.25V, +/-200mA)							
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	COMP	6	0	
CY8C20666 (8C20666AC)	4836589	610852813	Malaysia-CA	COMP	6	0	
CY8C20666 (8C20666AC)	4837410	410.23.02	Promex	COMP	6	0	

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Reliability Test Data

QTP #: 083401

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: ESD-HUMAN BODY CIRCUIT PER JESD22, METHOD A114, (2,200V)							
CY8C20566 (8C20566AC)	4810486	610830371	CML-R	2200	8	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	2200	8	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	2200	8	0	
STRESS: ESD-HUMAN BODY CIRCUIT PER JESD22, METHOD A114, (3,300V)							
CY8C20566 (8C20566AC)	4810486	610830371	CML-R	3300	3	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	3300	3	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	3300	3	0	
STRESS: ESD-MACHINE MODEL, (200V)							
CY8C20236A (8C202662A)	4126494	611143319	KOREA-L	200	5	0	
CY8C20236A (8C202662A)	4125077	611143627	PHIL-MB	200	5	0	
STRESS: ESD-MACHINE MODEL, (220V)							
CY8C20566 (8C20566AC)	4810486	610830371	CML-R	220	6	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	220	6	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	220	6	0	
STRESS: ESD-MACHINE MODEL, (275V)							
CY8C20566 (8C20566AC)	4810486	610830371	CML-R	275	3	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	275	3	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	275	3	0	
STRESS: ESD-MACHINE MODEL, (330V)							
CY8C20566 (8C20566AC)	4810486	610830371	CML-R	330	3	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	330	3	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	330	3	0	
STRESS: DYNAMIC LATCH-UP (125C, 8.5V)							
CY8C20466 (8C20466AC)	4810486	610828990	Malaysia-CA COMP		5	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA COMP		5	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA COMP		5	0	



Reliability Test Data
QTP #: 083401

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE (150, 2.1V, Vcc Max)							
CY8C20566 (8C20566AC)	4827949	610844164	CML-R	48	1002	0	
CY8C20566 (8C20566AC)	4815537	610835437	CML-R	48	1008	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	48	1004	1	Read NV Latch (1)
CY8C20466 (8C20466AC)	4836589	610851747	Malaysia-CA	48	1004	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE REGULATOR ON (150, 5V, Vcc Max)							
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	48	45	0	
CY8C20566 (8C20566AC)	4835945	610848270	CML-R	48	45	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE REGULATOR ON (125C, 5V, Vcc Max)							
CY8C20466 (8C20466AC)	4810486	610828990	Malaysia-CA	96	45	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE (150C, 2.1V, Vcc Max)							
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	80	390	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	500	390	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	80	390	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	500	390	0	
CY8C20466 (8C20466AC)	4836589	610851747	Malaysia-CA	80	390	0	
CY8C20466 (8C20466AC)	4836589	610851747	Malaysia-CA	500	390	0	
STRESS: HIGH TEMP STEADY STATE LIFE TEST (150C, 2.1V)							
CY8C20466 (8C20466AC)	4810486	610828990	Malaysia-CA	80	77	0	
CY8C20466 (8C20466AC)	4810486	610828990	Malaysia-CA	168	77	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	80	77	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	168	77	0	
CY8C20566 (8C20566AC)	4835945	610848270	CML-R	80	77	0	
CY8C20566 (8C20566AC)	4835945	610848270	CML-R	168	77	0	
STRESS: LOW TEMPERATURE DYNAMIC OPERATING LIFE, -30C, 2.1V							
CY8C20566 (8C20566AC)	4815537	610835437	CML-R	500	77	0	
CY8C20566 (8C20566AC)	4835945	610848270	CML-R	500	77	0	

(1) Destroyed during failure analysis



Reliability Test Data

QTP #: 083401

Device	Fab Lot #	Assy Lot #	Assy Lot	Duration	Samp	Rej	Failure Mechanism
STRESS: HI-ACCEL SATURATION TEST (130C, 85%RH, 5.25V), PRE COND 192 HR 30C/60%RH (MSL3)							
CY8C20466 (8C20466AC)	4810486	610828990	Malaysia-CA	128	77	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	128	77	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	256	77	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	128	77	0	
STRESS: PRESSURE COOKER TEST (121C, 100%RH), 15 Psig, PRE COND 192 HR 30C/60%RH (MSL3)							
CY8C20466 (8C20466AC)	4810486	610828990	Malaysia-CA	168	77	0	
CY8C20466 (8C20466AC)	4810486	610828990	Malaysia-CA	333	77	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	168	77	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	288	77	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	168	77	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	288	77	0	
STRESS: TC COND. C -65C TO 150C, PRE COND 192 HRS 30C/60%RH (MSL3)							
CY8C20466 (8C20466AC)	4810486	610828990	Malaysia-CA	500	77	0	
CY8C20466 (8C20466AC)	4810486	610828990	Malaysia-CA	1000	77	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	500	77	0	
CY8C20466 (8C20466AC)	4815537	610834184	Malaysia-CA	1000	77	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	500	77	0	
CY8C20466 (8C20466AC)	4835945	610847274	Malaysia-CA	1000	77	0	



Reliability Test Data
ER114031

Device	Fab Lot #	Assy Lot #	Assy Lot	Duration	Samp	Rej	Failure Mechanism
STRESS: LOW TEMPERATURE STORAGE, -40C, No Bias							
CY8C20236A (8C202662A)	4137730	611155459	L-KOREA	1000	100	0	



Reliability Test Data

QTP #: 113905

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: ACOUSTIC, MSL3							
CY8CTMA443 (8C20401B)	4140358	611153802	CML-RA	COMP	15	0	
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	COMP	15	0	
CY8CTMA443 (8C20401A)	4129433	611148871	G-TAIWAN	COMP	15	0	
CY8CTMA443 (8C20401A)	4131142	611148867	G-TAIWAN	COMP	15	0	
STRESS: BOND PULL							
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	COMP	10	0	
CY8CTMA443 (8C20401A)	4129433	611148871	G-TAIWAN	COMP	10	0	
CY8CTMA443 (8C20401A)	4131142	611148867	G-TAIWAN	COMP	10	0	
STRESS: DATA RETENTION, 150C							
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	500	80	0	
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	1000	80	0	
STRESS: DYE PENETRANT TEST							
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	COMP	15	0	
STRESS: ENDURANCE							
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	168	80	0	
STRESS: ESD-CHARGE DEVICE MODEL, (500V)							
CY8CTMA443 (8C20401B)	4140358	611153802	CML-RA	COMP	9	0	
STRESS: ESD-HUMAN BODY MODEL PER JESD22, METHOD A114, (1100V)							
CY8CTMA443 (8C20401B)	4140358	611153802	CML-RA	COMP	3	0	
STRESS: ESD-HUMAN BODY MODEL PER JESD22, METHOD A114, (1600V)							
CY8CTMA443 (8C20401B)	4140358	611153801	CML-RA	COMP	8	0	
STRESS: HI-ACCEL SATURATION TEST (130C, 85%RH, 5.5V), PRE COND 192 HR 30C/60%RH (MSL3)							
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	128	80	0	
CY8CTMA443 (8C20401A)	4129433	611148871	G-TAIWAN	128	78	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE REG-ON (150C, 6.0V, Vcc Max)							
CY8CTMA443 (8C20401A)	4130520	611147745	G-TAIWAN	48	45	0	



Reliability Test Data

QTP #: 113905

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE (150C, 2.07V, Vcc Max)							
CY8CTMA443 (8C20401B)	4140358	611153802	CML-RA	48	1492	0	
CY8CTMA443 (8C20401B)	4140358	611153800	CML-RA	48	1074	2	ISB Deep Sleep, CAR#201201012
CY8CTMA443 (8C20401B)	4140358	611153800	CML-RA	48	418	1	ISB Deep Sleep, CAR#201201012
CY8CTMA443 (8C20401B)	4141585	611156224	G-TAIWAN	48	1500	0	
CY8CTMA443 (8C20401A)	4129433	611148871	G-TAIWAN	48	1000	0	
CY8CTMA443 (8C20401A)	4131142	611148870	G-TAIWAN	48	500	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE (150C, 2.07V, Vcc Max)							
CY8CTMA443 (8C20401A)	4129433	611148871	G-TAIWAN	80	116	0	
CY8CTMA443 (8C20401A)	4129433	611148871	G-TAIWAN	500	116	0	
STRESS: INTERNAL VISUAL							
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	COMP	5	0	
STRESS: PRESSURE COOKER TEST (121C, 100%RH, 15 Psig), PRE COND 192 HR 30C/60%RH (MSL3)							
CY8CTMA443 (8C20401B)	4140358	611153802	CML-RA	168	77	0	
CY8CTMA443 (8C20401B)	4140358	611153802	CML-RA	288	77	0	
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	168	80	0	
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	288	80	0	
CY8CTMA443 (8C20401A)	4129433	611148871	G-TAIWAN	168	80	0	
CY8CTMA443 (8C20401A)	4129433	611148871	G-TAIWAN	288	80	0	
STRESS: TEMPERATURE CYCLE (COND. C, -65C TO 150C), PRE COND 192 HR 30C/60%RH (MSL3)							
CY8CTMA443 (8C20401B)	4140358	611153802	CML-RA	500	83	0	
CY8CTMA443 (8C20401B)	4140358	611153802	CML-RA	1000	83	0	
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	500	79	0	
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	1000	79	0	
CY8CTMA443 (8C20401A)	4129433	611148871	G-TAIWAN	500	80	0	
CY8CTMA443 (8C20401A)	4129433	611148871	G-TAIWAN	1000	80	0	
CY8CTMA443 (8C20401A)	4131142	611148867	G-TAIWAN	500	80	0	
CY8CTMA443 (8C20401A)	4131142	611148867	G-TAIWAN	1000	80	0	



Reliability Test Data

QTP #: 113905

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: STATIC LATCH-UP TESTING (125C, 8.25V, +/-140mA)							
CY8CTMA443 (8C20401B)	4140358	611153802	CML-RA	COMP	6	0	
STRESS: THERMAL JUNCTION MEASUREMENT							
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	COMP	2	0	
STRESS: THERMAL SHOCK (COND. B, -55C TO 125C)							
CY8CTMA443 (8C20401A)	4130520	611147744	G-TAIWAN	200	80	0	



Reliability Test Data QTP #: 151304

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: DATA RETENTION, PLASTIC, 150C							
CYPD1132 (8C44110A)	4251883	611301729	TAIWAN-G	500	70	0	
CYPD1132 (8C44110A)	4251883	611301729	TAIWAN-G	1000	70	0	
STRESS: ENDURANCE							
CYPD1132 (8C44110A)	4251883	611302906	TAIWAN-G	168	80	0	
CYPD1132 (8C44110A)	4251883	611302906	TAIWAN-G	500	80	0	
STRESS: ESD-CHARGE DEVICE MODEL, (500V)							
CYPD1132 (8C44110A)	4251883	611302905	TAIWAN-G	COMP	9	0	
CYPD1132 (8C44110A)	4251883	611303718	TAIWAN-G	COMP	9	0	
CYPD1132 (8C44110A)	4251883	611302173	CML-RA	COMP	9	0	
STRESS: ESD-CHARGE DEVICE MODEL, (1000V)							
CYPD1132 (8C44110A)	4251883	611302905	TAIWAN-G	COMP	3	0	
CYPD1132 (8C44110A)	4251883	611303718	TAIWAN-G	COMP	3	0	
CYPD1132 (8C44110A)	4251883	611302173	CML-RA	COMP	3	0	
STRESS: ESD-CHARGE DEVICE MODEL, (1250V)							
CYPD1132 (8C44110A)	4251883	611302905	TAIWAN-G	COMP	3	0	
CYPD1132 (8C44110A)	4251883	611303718	TAIWAN-G	COMP	3	0	
CYPD1132 (8C44110A)	4251883	611302173	CML-RA	COMP	3	0	
STRESS: ESD-HUMAN BODY CIRCUIT PER JESD22, METHOD A114, (2,200V)							
CYPD1132 (8C44110A)	4251883	611302905	TAIWAN-G	COMP	9	0	
STRESS: ESD-HUMAN BODY CIRCUIT PER JESD22, METHOD A114, (3,300V)							
CYPD1132 (8C44110A)	4251883	611302905	TAIWAN-G	COMP	3	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE (150, 2.07V, Vcc Max)							
CYPD1132 (8C44110A)	4251883	611303750	TAIWAN-G	48	189	0	
CYPD1132 (8C44110A)	4251883	611302906	TAIWAN-G	48	1111	0	
CYPD1132 (8C44110A)	4251883	611307128N	TAIWAN-G	48	1093	0	
CYPD1132 (8C44110A)	4251883	611308275	TAIWAN-G	48	1049	0	
CYPD1132 (8C44110A)	4251883	611308282	TAIWAN-G	48	1049	0	



Reliability Test Data

QTP #: 151304

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE REGULATOR ON (150, 2.07V, Vcc Max)							
CYPD1132 (8C44110A)	4251883	611302906	TAIWAN-G	48	39	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE (150C, 2.07V, Vcc Max)							
CYPD1132 (8C44110A)	4251883	611302906	TAIWAN-G	80	151	0	
CYPD1132 (8C44110A)	4251883	611302906	TAIWAN-G	500	151	0	
STRESS: PRE/POST LFR PARAMETER ASSESSMENT							
CYPD1132 (8C44110A)	4251883	611303750	TAIWAN-G	COMP	32	0	
STRESS: PRESSURE COOKER TEST (121C, 100%RH), 15 Psig, PRE COND 192 HR 30C/60%RH (MSL3)							
CYPD1132 (8C44110A)	4251883	611301729	TAIWAN-G	168	77	0	
CYPD1132 (8C44110A)	4251883	611301729	TAIWAN-G	288	77	0	
STRESS: STATIC LATCH-UP (85C, +/-140mA)							
CYPD1132 (8C44110A)	4251883	611302905	TAIWAN-G	COMP	6	0	
STRESS: STATIC LATCH-UP (85C, +/-180mA)							
CYPD1132 (8C44110A)	4251883	611302905	TAIWAN-G	COMP	2	0	
STRESS: STATIC LATCH-UP (125C, +/-140mA)							
CYPD1132 (8C44110A)	4251883	611302905	TAIWAN-G	COMP	2	0	
STRESS: TC COND. C -65C TO 150C, PRE COND 192 HRS 30C/60%RH (MSL3)							
CYPD1132 (8C44110A)	4251883	611301729	TAIWAN-G	500	77	0	
CYPD1132 (8C44110A)	4251883	611301729	TAIWAN-G	1000	76	0	



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